

FORM PTO-1449	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTORNEY DOCKET NO. 1607.1001 CIP/C	APPLICATION NO. 10/612,042
LIST OF REFERENCES CITED BY APPLICANT  (Use several sheets if necessary)		FIRST NAMED INVENTOR Prakash Khatri	
		FILING DATE July 3, 2003	GROUP ART UNIT 1764

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NO.	DATE	NAME	CLASS	SUB- CLASS	FILING DATE
<i>gsh</i>	AA	3,669,884	6/13/72	Wright	252	36	
<i>gsh</i>	AB	4,738,737	4/19/88	Runde et al.	156	91	
<i>gsh</i>	AC	4,803,100	2/7/89	Ameen et al.	427	387	
<i>gsh</i>	AD	5,167,851	12/1/92	Jamison et al.	252	74	
<i>gsh</i>	AE	5,194,480	3/16/93	Block et al.			
<i>gsh</i>	AF	5,250,209	10/5/93	Jamison et al.	252	74	
<i>gsh</i>	AG	5,298,791	3/29/94	Liberty et al.	257	707	
<i>gsh</i>	AH	5,904,796	5/18/99	Freuler et al.	156	278	
<i>gsh</i>	AI	6,049,458	4/11/00	Lee et al.	361	705	
<i>gsh</i>	AJ	6,054,198	4/25/00	Bunyan et al.	428	40.5	
<i>gsh</i>	AK	6,059,116	5/9/00	Hinshaw et al.	206	714	
<i>gsh</i>	AL	6,114,429	9/5/00	Yamada, et al.	524	432	
<i>gsh</i>	AM	6,143,076	11/7/00	Rasmussen, et al.	118	411	
<i>gsh</i>	AN	6,174,841	1/01	Yamada et al.	508	172	
<i>gsh</i>	AO	6,255,257	7/01	Yamada et al.	508	172	
<i>gsh</i>	AP	6,286,212	9/01	Easton	29	890.03	
<i>gsh</i>	AQ	6,475,962	11/02	Khatri	508	161	



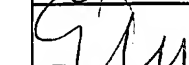



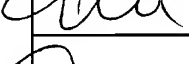










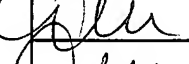
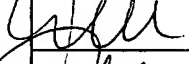
**FOREIGN PATENT DOCUMENTS**

		DOCUMENT NO.	DATE	COUNTRY	CLASS	SUB-CLASS	TRANSLATION	
							YES	NO
<i>See</i> <i>Ann</i>	AR	WO/00/36893	6/22/00	WIPO	—	—		
	AS	EP 0906945	4/7/99	EPC	—	—		

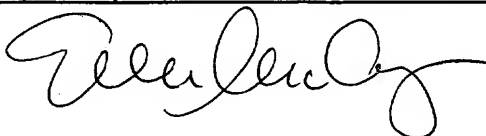
**OTHER REFERENCES** (Including Author, Title, Date, Pertinent Pages, Etc.)

<i>See</i>	AT	Advanced Thermal Interface Material: 'Dry-To-The-Touch' Thermal Grease by Khatri and Ziemski, March, 2001.
<i>See</i>	AU	"Sprayable Thermal Grease Dramatically Reduces Labor While Offering Other Unique Advantages" by Khatri and Ziemski, 1999.
<i>See</i>	AV	Article entitled, "Thermal Isolators", <u>PCIM</u> , April 1999 (pp. 57-61)
<i>See</i>	AW	Chomerics Technical Bulletin 69, "CHO-TERM T500", 10/99 (2pgs)
<i>See</i>	AX	Power Devices, Inc. "Powerstrate" Advertisement (1 pg.), date unknown
<i>See</i>	AY	Article entitled, "Differential Phase Change Thermal Interface Materials", Technological Horizons (2 pgs.), date unknown
<i>See</i>	AZ	Article entitled "Thermal Gap Fillers," <u>PCIM</u> , September 1999 (pp. 24-25, 27)
<i>See</i>	BA	Article entitled "Navigating the Maze of Thermal Interface Materials," Electronic Product Supplement, ( <a href="http://www.electronicproducts.com">http://www.electronicproducts.com</a> ) Fall, 1999 (5 pp.)
<i>See</i>	BB	Article entitled "Thermal Resistance of Interface Materials as a Function of Pressure," Latham, (2 pp.), ( <a href="http://www.electronics-cooling.com/Resources/EC_Articles/SEP96/sep96_tb.htm">http://www.electronics-cooling.com/Resources/EC_Articles/SEP96/sep96_tb.htm</a> ).
<i>See</i>	BC	Wakefield Engineering advertisement "Thermal Compounds, Adhesives, Interface Materials, Hardware, Installation Tools (1 pg.), believed dated 1997 or before.
<i>See</i>	BD	Bergquist Company Brochure "Sil-Pad Design Guide" 1997-1998 (1 pg.)
<i>See</i>	BE	Chomerics Company (Division of Parker-Hannifin) Advertisement, (1 pg.), from <u>Electronics Cooling</u> , Vol. 7, No. 1, February 2001
<i>See</i>	BF	Fujipoly Company advertisement from <u>PCIM</u> , January 2000, page 14
<i>See</i>	BG	MHW brochure regarding Keratherm® (2 pp.), February 1999
<i>See</i>	BH	MHW International Corp. advertisement from <u>Electronics Cooling</u> , Vol. 7, No. 1, February 2001, page 13
<i>See</i>	BI	W.L. Gore & Assoc. advertisement (1 pg.) from <u>Electronic Packaging and Production</u> , June 2001
<i>See</i>	BJ	Emerson & Cuming (division of National Starch and Chemical Company), advertisement (1 pg.)
<i>See</i>	BK	Honeywell advertisement (1 pg.) from <u>Electronics Cooling</u> , Vol. 7, No. 1, February 2001

1.53(b) Continuation of Serial No.: 09/951,501  
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SHEET 3 OF 3

	BL	"Electrolube's Unique Heat Transfer Compound Aerosol Optimises Board Thermal Performance," July 28, 2000 website pages (5 pp.)
	BM	AOS brochure describing thermal greases.
	BN	Article entitled "Attaching Heat Sinks to Components," Electronic Packaging & Production, pp. 42-46, July 1997
	BO	Article entitled "Thermal Interface Materials," deSorgo et al., found at <a href="http://www.cooling-electronics.com/Resources/EC_Articles/SEP96/sep96_01.htm">http://www.cooling-electronics.com/Resources/EC_Articles/SEP96/sep96_01.htm</a> (6 pp.)
	BP	Article entitled "Thermal Management Materials and Designs," <u>Electronic Packaging and Production</u> , October 2000 (pgs. 50-57).
	BQ	Thermalloy Company Press Release (1 pg.), December 18, 1996.
	BR	Article entitled "Cooling Technologies - Work With Microprocessors Points the Way to Thermal Management Improvements for Power Semiconductors," <u>PCIM</u> , May 1999 (6 pp.)
	BS	Article entitled "Test Methods for Characterizing the Thermal Transmission Properties of Phase-change Thermal Interface Materials," ( <a href="http://www.electronics-cooling.com/html1/1999_may_article1.html">http://www.electronics-cooling.com/html1/1999_may_article1.html</a> ), May 1999 (9 pp.)
	BT	Brochure for Thermagon Company (5 pp.), ©1997.
	BU	Brochure for Orcus, Inc., (3 pp.), ©1998.
	BV	Brochure for Bergquist Company (5 pp.), ©1998.
	BW	Advertisement for Bergquist Company "Thermal Performance you must see to believe," (1 pg.), undated
	BX	Brochure for Power Devices Company (11 pp.), ©1996
	BY	Brochure for Chomerics Company (6 pp.), October 1999
	BZ	Advertisement for Chomerics Company's "Therm-A-Gap" Gap Filling Materials, (1 pg.), October 1999
	CA	Advertisement for "GAP PAD VO," (1 pg.), undated
	CB	Advertisement for Fujipoly Company's "SARCON Thermal Management Components," (1 pg.), undated.
	CC	Advertisement for Fujipoly Company's "SARCON Heat Sink Gel Pads," (1 pg.), undated
	CD	Abstract regarding WO 0036893, entitled, "Method of Applying a Phase-Change Thermal Interface Material" published June 22, 2000 (1 pg.)

NAME:



DATE

20 July 2004